

74ABT2244

Octal Buffer/Line Driver with 25Ω Series Resistors in the Outputs

General Description

The ABT2244 is an octal buffer and line driver designed to drive the capacitive inputs of MOS memory drivers, address drivers, clock drivers, and bus-oriented transmitters/receivers.

The 25Ω series resistors in the outputs reduce ringing and eliminate the need for external resistors.

Features

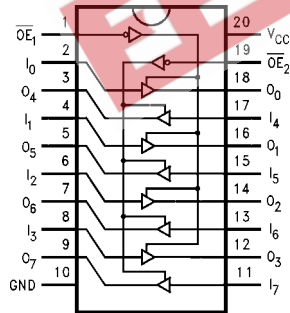
- Guaranteed latchup protection
- High impedance glitch-free bus loading during entire power up and power down cycle
- Nondestructive hot insertion capability

Ordering Code:

Order Number	Package Number	Package Description
74ABT2244CSC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide Body
74ABT2244CSJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ABT2244CMSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74ABT2244CMTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74ABT2244CPC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices are also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

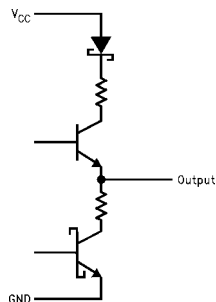
Connection Diagram



Pin Descriptions

Pin Names	Description
$\overline{OE}_1, \overline{OE}_2$	Output Enable Input (Active LOW)
I_0-I_7	Inputs
O_0-O_7	Outputs

Schematic of Each Output



Truth Table

\overline{OE}_1	I_{0-3}	O_{0-3}	\overline{OE}_2	I_{4-7}	O_{4-7}
H	X	Z	H	X	Z
L	H	H	L	H	H
L	L	L	L	L	L

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

Absolute Maximum Ratings ^(Note 1)		Recommended Operating Conditions	
Storage Temperature	-65°C to +150°C	Free Air Ambient Temperature	-40°C to +85°C
Ambient Temperature under Bias	-55°C to +125°C	Supply Voltage	+4.5V to +5.5V
Junction Temperature under Bias	-55°C to +150°C	Minimum Input Edge Rate ($\Delta V/\Delta t$)	
V _{CC} Pin Potential to Ground Pin	-0.5V to +7.0V	Data Input	50 mV/ns
Input Voltage (Note 2)	-0.5V to +7.0V	Enable Input	20 mV/ns
Input Current (Note 2)	-30 mA to +5.0 mA		
Voltage Applied to Any Output			
in the Disabled or			
Power-off State	-0.5V to 5.5V		
in the HIGH State	-0.5V to V _{CC}		
Current Applied to Output			
in LOW State (Max)	twice the rated I _{OL} (mA)		
DC Latchup Source Current			
(Across Comm Operating Range)	-300 mA		
Over Voltage Latchup (I/O)	10V		

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

DC Electrical Characteristics

Symbol	Parameter	Min	Typ	Max	Units	V _{CC}	Conditions
V _{IH}	Input HIGH Voltage	2.0			V		Recognized HIGH Signal
V _{IL}	Input LOW Voltage			0.8	V		Recognized LOW Signal
V _{CD}	Input Clamp Diode Voltage			-1.2	V	Min	I _{IN} = -18 mA
V _{OH}	Output HIGH	2.5			V	Min	I _{OH} = -3 mA
		2.0			V	Min	I _{OH} = -32 mA
V _{OL}	Output LOW Voltage			0.8	V	Min	I _{OL} = 15 mA
I _{IH}	Input HIGH Current			1	μA	Max	V _{IN} = 2.7V (Note 4)
				1	μA	Max	V _{IN} = V _{CC}
I _{BVI}	Input HIGH Current Breakdown Test			7	μA	Max	V _{IN} = 7.0V
I _{IL}	Input LOW Current			-1	μA	Max	V _{IN} = 0.5V (Note 4)
				-1	μA	Max	V _{IN} = 0.0V
V _{ID}	Input Leakage Test	475			V	0.0	I _{ID} = 1.9 μA All Other Pins Grounded
I _{OZH}	Output Leakage Current			10	μA	0 - 5.5V	V _{OUT} = 2.7V; \overline{OEn} = 2.0V
I _{OZL}	Output Leakage Current			-10	μA	0 - 5.5V	V _{OUT} = 0.5V; \overline{OEn} = 2.0V
I _{OS}	Output Short-Circuit Current	-100		-275	mA	Max	V _{OUT} = 0.0V
I _{CEX}	Output HIGH Leakage Current			50	μA	Max	V _{OUT} = V _{CC}
I _{ZZ}	Bus Drainage Test			100	μA	0.0	V _{OUT} = 5.5V; All Others GND
I _{CCH}	Power Supply Current			50	μA	Max	All Outputs HIGH
I _{CCL}	Power Supply Current			30	mA	Max	All Outputs LOW
I _{CCZ}	Power Supply Current			50	μA	Max	\overline{OEn} = V _{CC} All Others at V _{CC} or GND
I _{CCT}	Additional Outputs Enabled I _{CC} /Input	Outputs Enabled		2.5	mA		V _I = V _{CC} - 2.1V
		Outputs 3-STATE		2.5	mA	Max	Enable Input V _I = V _{CC} - 2.1V
		Outputs 3-STATE		50	μA		Data Input V _I = V _{CC} - 2.1V All Others at V _{CC} or GND
I _{CCD}	Dynamic I _{CC} (Note 4)	No Load		0.1	mA/ MHz	Max	Outputs OPEN \overline{OEn} = GND (Note 3) One Bit Toggling, 50% Duty Cycle

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

Note 3: For 8 bits toggling, I_{CCD} < 0.8 mA/MHz.

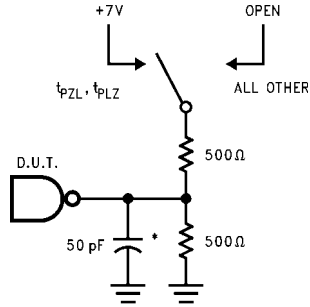
Note 4: Guaranteed, but not tested.

AC Electrical Characteristics							
(SOIC and SSOP Package)							
Symbol	Parameter	T _A = +25°C V _{CC} = +5V C _L = 50 pF			T _A = -40°C to +85°C V _{CC} = 4.5V-5.5V C _L = 50 pF		Units
		Min	Typ	Max	Min	Max	
t _{PLH}	Propagation	1.0	2.2	3.9	1.0	3.9	ns
t _{PHL}	Delay Data to Outputs	1.0	2.9	4.4	1.0	4.4	
t _{PZH}	Output Enable	1.5	3.7	6.0	1.5	6.0	ns
t _{PZL}	Time	2.1	4.3	7.0	2.1	7.0	
t _{PHZ}	Output Disable	1.7	3.5	5.8	1.7	5.8	ns
t _{PLZ}	Time	1.7	3.7	5.8	1.7	5.8	

Capacitance				
Symbol	Parameter	Typ	Units	Conditions T _A = 25°C
C _{IN}	Input Capacitance	5.0	pF	V _{CC} = 0V
C _{OUT} (Note 5)	Output Capacitance	9.0	pF	V _{CC} = 5.0V

Note 5: C_{OUT} is measured at frequency f = 1 MHz, per MIL-STD-883, Method 3012.

AC Loading



*Includes jig and probe capacitance

FIGURE 1. Standard AC Test Load

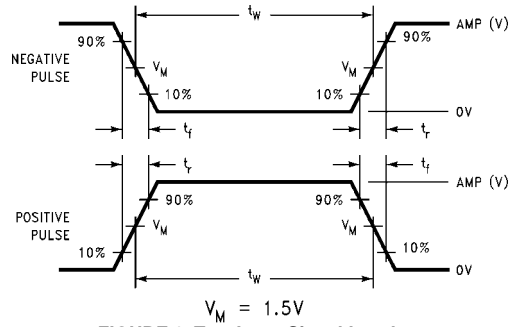


FIGURE 2. Test Input Signal Levels

Amplitude	Rep. Rate	t_w	t_r	t_f
3.0V	1 MHz	500 ns	2.5 ns	2.5 ns

FIGURE 3. Test Input Signal Requirements

AC Waveforms

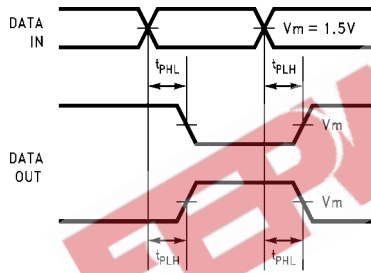


FIGURE 4. Propagation Delay Waveforms for Inverting and Non-Inverting Functions

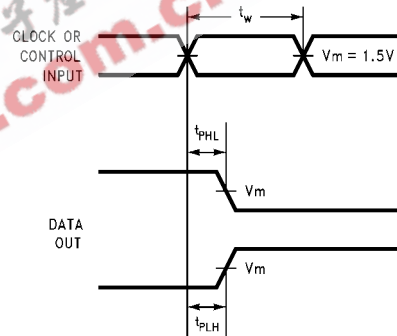


FIGURE 6. Propagation Delay, Pulse Width Waveforms

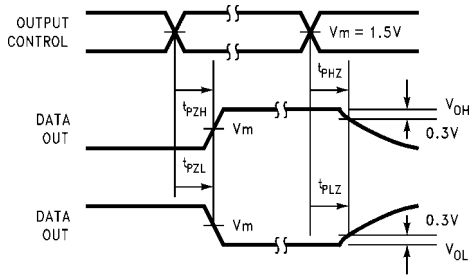


FIGURE 5. 3-STATE Output HIGH and LOW Enable and Disable Times

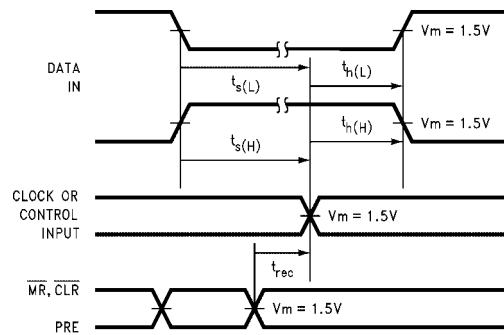
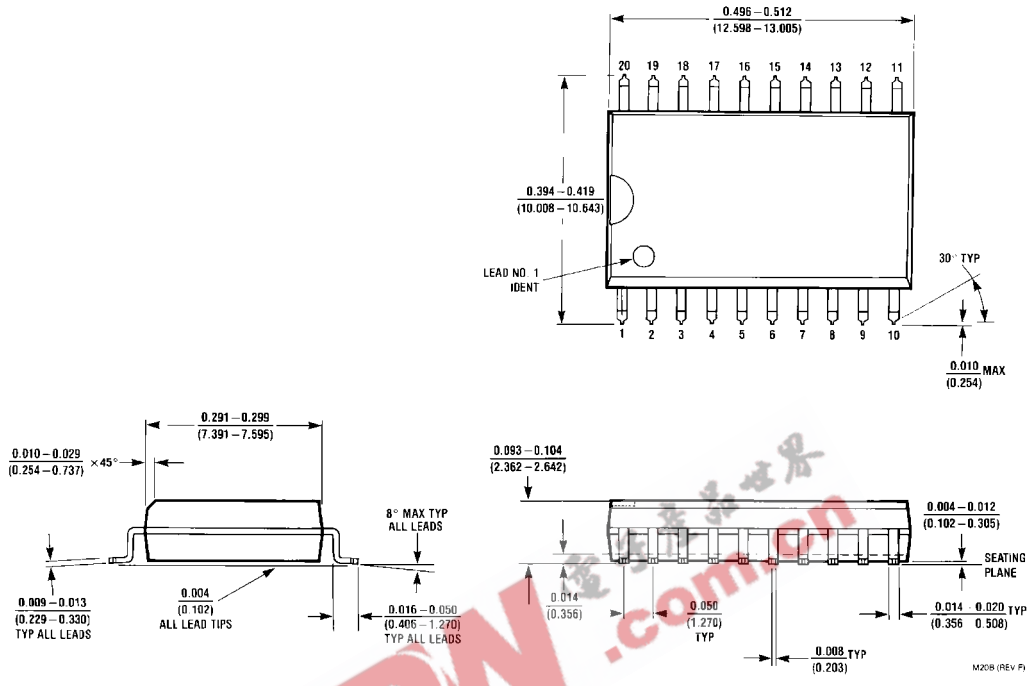


FIGURE 7. Setup Time, Hold Time and Recovery Time Waveforms

Physical Dimensions inches (millimeters) unless otherwise noted



**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide Body
Package Number M20B**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1996.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1

DETAIL A

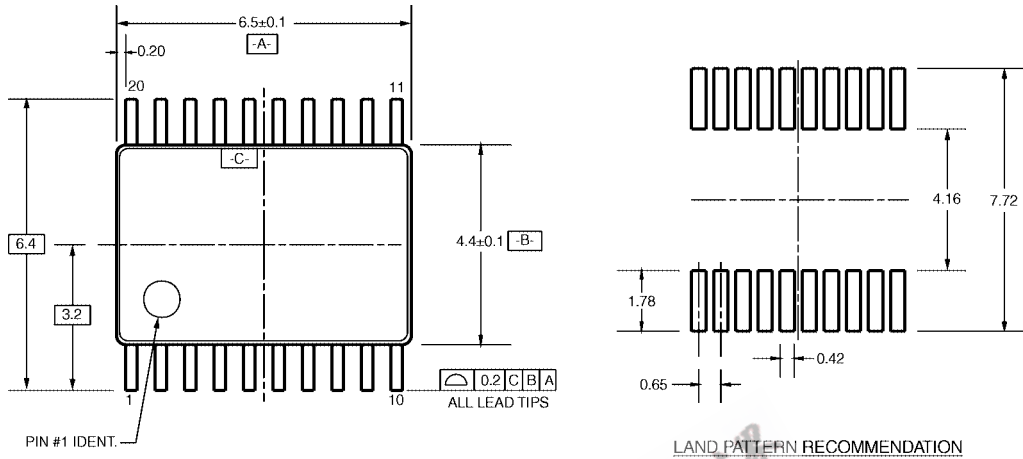
**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



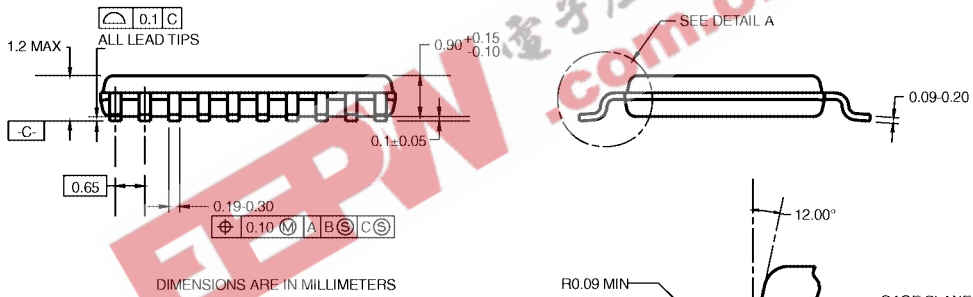
**20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
Package Number MSA20**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



PIN #1 IDENT.

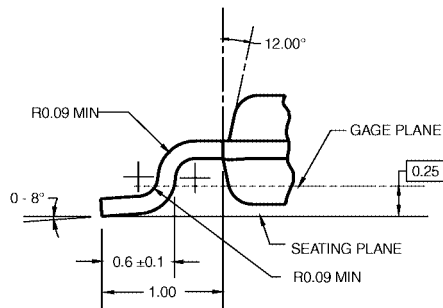
LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS

- NOTES:
- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.
 - B. DIMENSIONS ARE IN MILLIMETERS.
 - C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
 - D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

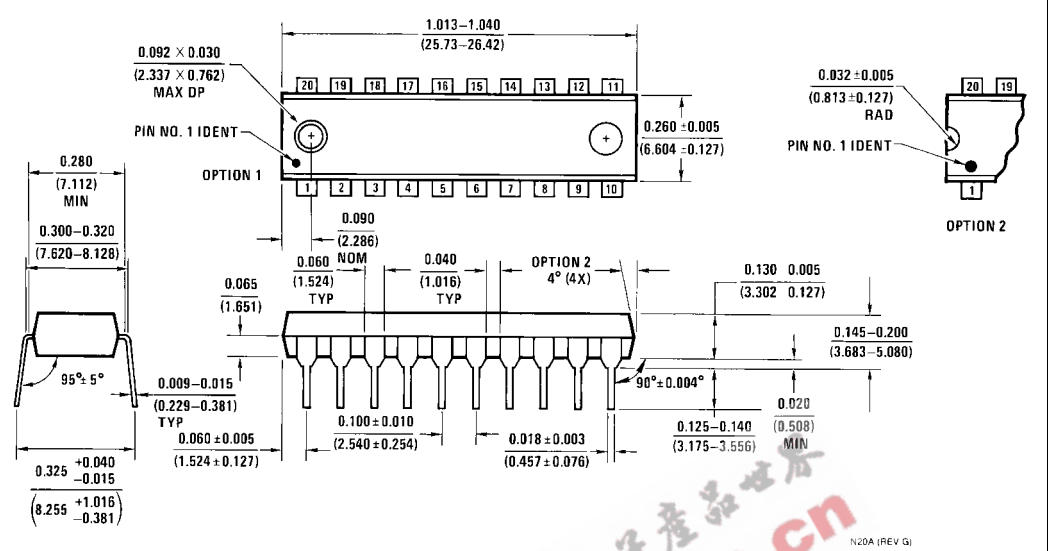
MTC20RevD1



DETAIL A

**20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC20**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
Package Number N20A

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